



SIMM Sockets — (MICRO-EDGE) with Plastic Latches

Product Facts

- Positive wipe occurs on each pad during insertion of module
- Redundant contact system
- Contact anti-overstress design
- Very low insertion force
- Free lateral movement of contacts in the housing
- Designed for robotic assembly methods
- Heat resistant housing materials
- Provides high density packaging
- Positive polarization of module
- Anti-overstress of latches helps to prevent breakage
- Recognized under the Component Program of Underwriters Laboratories Inc., File E28476 
- Certified by Canadian Standards Association File No. LR 7189 

Technical Documents

Product Specifications:
108-1095

Application Specifications:
114-1061

Instruction Sheet:
408-9413



Custom-made memory and logic modules are growing in popularity because they provide high functional density in economical, space-efficient packages. Following the example of the SIMM (Single In-Line Memory Module), manufacturers are surface-mounting memory or logic IC's on small printed circuit boards. To preserve the integrity of the IC's and to facilitate field replacement of damaged modules, most manufacturers choose to socket their modules; MICRO-EDGE SIMM sockets meet that need.

MICRO-EDGE SIMM sockets are offered in versions with .100 [2.54] and .050 [1.27] contact centerline spacing, in both single and dual row configurations. All are available in vertical and low profile designs for single and double-sided SIMM or logic modules.

All versions share the unique, low profile, high pressure tin-plated contact that accepts standard module board thickness and wipes the board pad during card installation. Contacts float within the housings to maintain a motion-free interface with board pads, even during uneven thermal expansion.

The housing is made from liquid crystal polymer, assuring strong, durable ramps and anti-stress latching features. Polarizing posts coincide with cutouts on the board to prevent misinsertion. To install a module board, the card cage fingers are angled into the socket's contacts, then the card is pivoted into position, where locking latches secure it.

Performance Characteristics

Current:
1 ampere max.

Termination Resistance (Dry Circuit):
30 milliohms max. (initial)

Dielectric Withstanding Voltage:
1.5 KVAC (.100 [2.54] centerline product)
1.0 KVAC (.050 [1.27] centerline product)

Insulation Resistance:
10,000 megohms min. (initial)

Capacitance:
1.0 picofarad max.

Operating Temperature:
-55°C to +105°C

Durability:
25 cycles min.

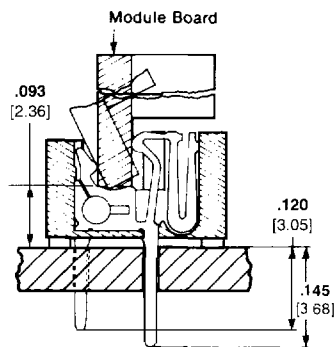
SIMM Sockets — with Plastic Latches, .050 [1.27] CL

Vertical Single Row

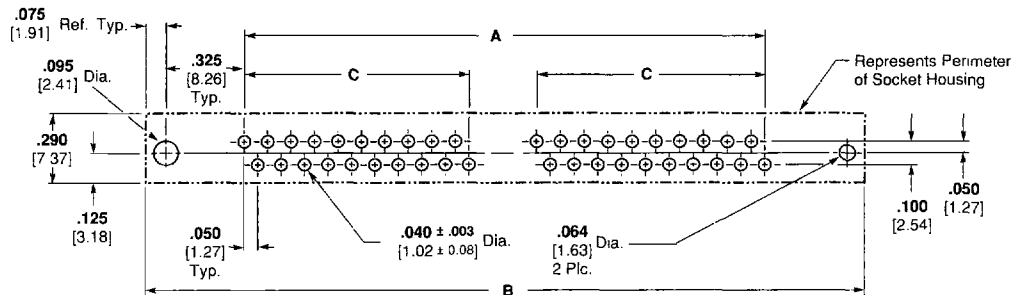
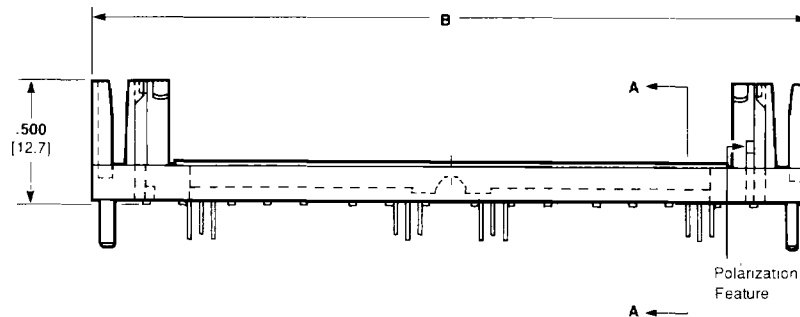
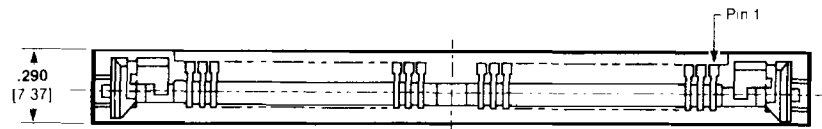
Material and Finish

Housing — Liquid Crystal Polymer (LCP) UL 94V-0

Contacts — Phosphor bronze with .000200 [0.00508] min. thick tin-lead over .000050 [0.00127] min. thick nickel or .000030 [0.00076] min. thick gold on contact area and .000150 [0.0038] min. thick tin-lead on solder tails, all over .000050 [0.00127] min. thick nickel



Section A-A



Recommended PC Board Hole Pattern

No. of Pos.	Dimensions			Tin Plate	Gold Plate
	A	B	C		
64	3.350 85.09	4.150 105.41	1.550 39.37	821824-6	821825-6
68	3.550 90.17	4.350 110.49	1.650 41.91	821824-7	—
72	3.750 95.25	4.550 115.57	1.750 44.45	821824-8	821825-8
80	4.150 105.41	4.950 125.73	1.950 49.53	821824-9	821825-9

Note: See page 30 for module layout.

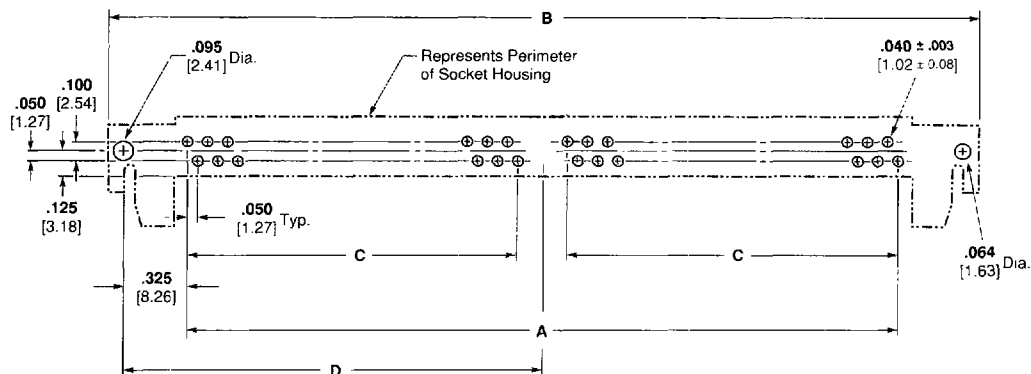
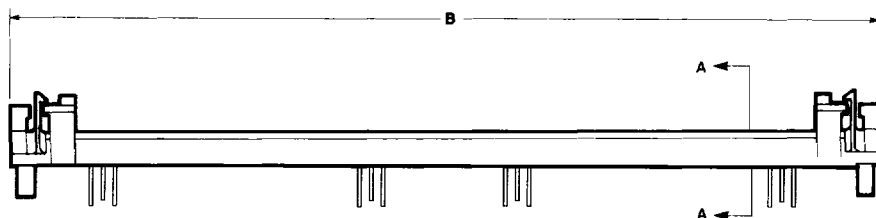
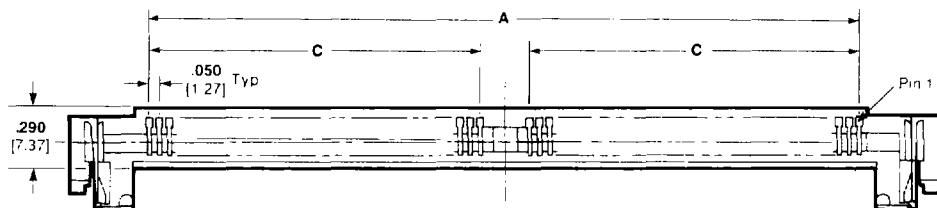
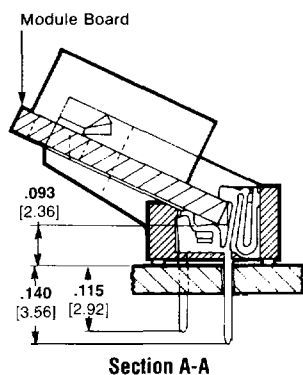
SIMM Sockets — with Plastic Latches, .050 [1.27] CL (Continued)

Low Profile (25°) Single Row (Standard Footprint)

Material and Finish

Housing — Liquid Crystal Polymer (LCP) UL 94V-0

Contacts — Phosphor bronze with .000200 [0.00508] min. thick tin-lead over .000050 [0.00127] min. thick nickel or .000030 [0.00076] min. thick gold on contact area and .000150 [0.0038] min. thick tin-lead on solder tails, all over .000050 [0.00127] min. thick nickel



Recommended PC Board Hole Pattern

No. of Pos.	Dimensions				Tin Plate	Gold Plate
	A	B	C	D		
64	3.350 85.09	4.150 105.41	1.550 39.37	2.000 50.80	821947-5	821950-5
68	3.550 90.17	4.350 110.49	1.650 41.91	2.100 53.34	821947-6	—
72	3.750 95.25	4.550 115.57	1.750 44.45	2.200 55.88	821947-7	821950-7
80	4.150 105.41	4.950 125.73	1.950 49.53	2.400 60.96	821947-8	821950-8

Note: See page 30 for module layout.

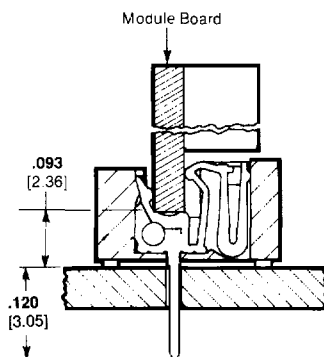
SIMM Sockets — with Plastic Latches, .100 [2.54] CL

Vertical Single Row

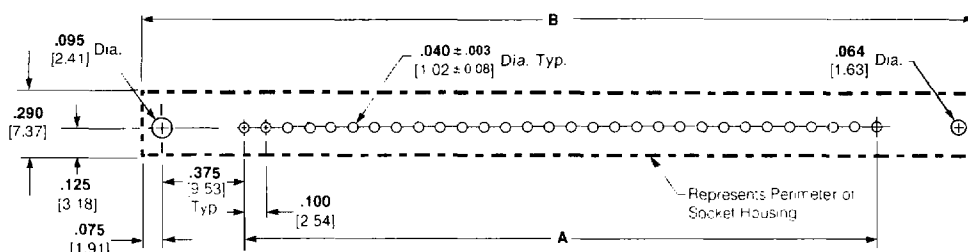
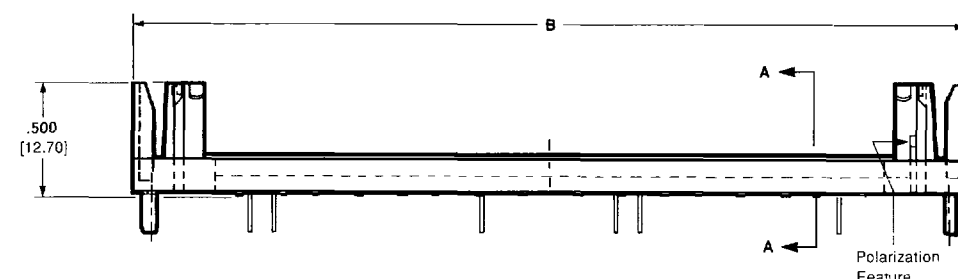
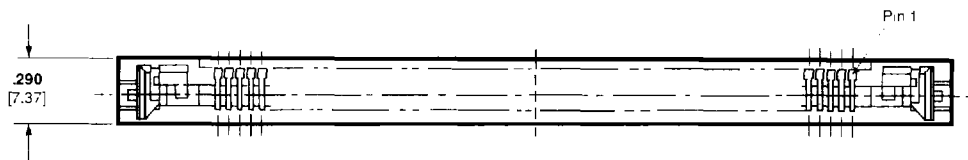
Material and Finish

Housing — Liquid Crystal Polymer (LCP) UL 94V-0

Contacts — Phosphor bronze with .000200 [0.00508] min. thick tin-lead over .000050 [0.00127] min. thick nickel or .000030 [0.00076] min. thick gold on contact area and .000150 [0.0038] min. thick tin-lead on solder tails, all over .000050 [0.00127] min. thick nickel



Section A-A



Recommended PC Board Hole Pattern

No. of Pos.	Dimensions		Tin Plate	Gold Plate
	A	B		
22	2.100 53.34	3.000 76.20	821828-1	821829-1
30	2.900 73.66	3.800 96.52	821828-2	821829-2
35	3.400 86.36	4.300 109.22	821828-3	—
42	4.100 104.14	5.000 127.00	821828-5	—

Note: See page 30 for module layout.

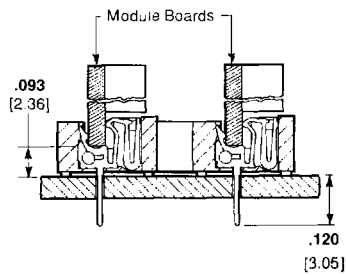
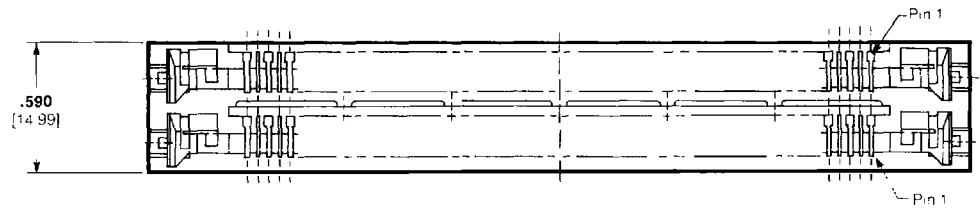
SIMM Sockets — with Plastic Latches, .100 [2.54] CL (Continued)

Vertical Dual Row
(.100 x .300 [2.54 x 7.62]
Spacing)

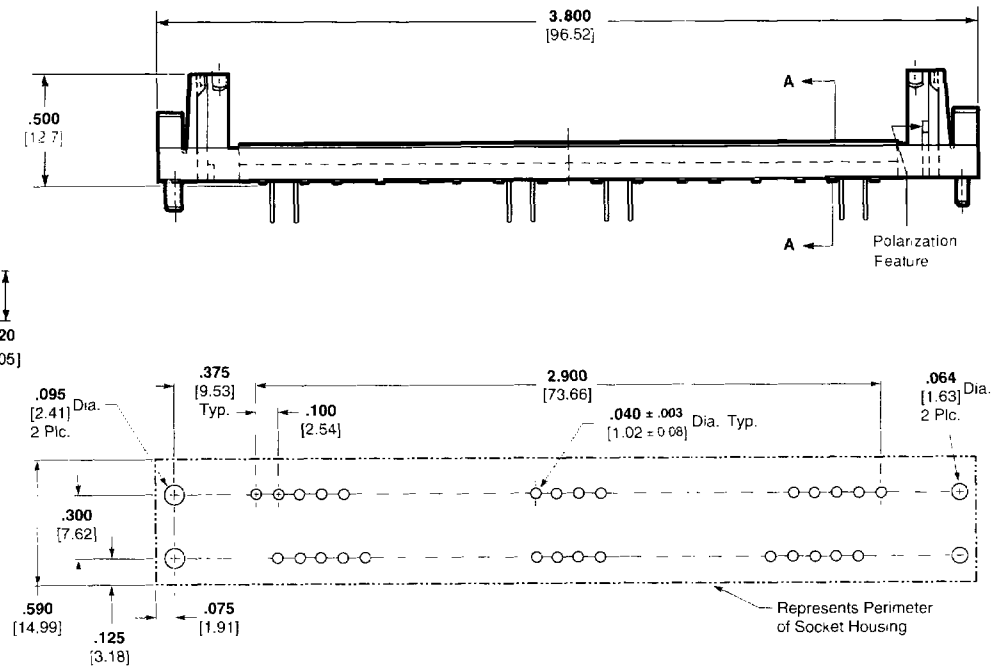
Material and Finish

Housing—Liquid Crystal Polymer
 (LCP) UL 94V-0

Contacts—Phosphor bronze with
 .000200 [0.00508] min. thick tin-
 lead over .000050 [0.00127] min.
 thick nickel on contact area and
 .000150 [0.0038] min. thick tin-lead
 on solder tails, all over .000050
 [0.00127] min. thick nickel



Section A-A



Recommended PC Board Hole Pattern

No. of Pos.	Tin Plate
30	821885-2

Notes:

1. See page 30 for module layout.
2. Other sizes can be made available. Contact AMP Incorporated.

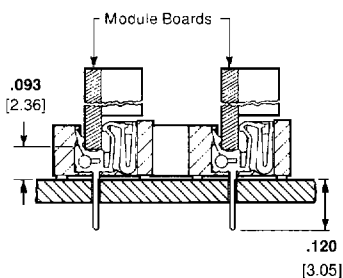
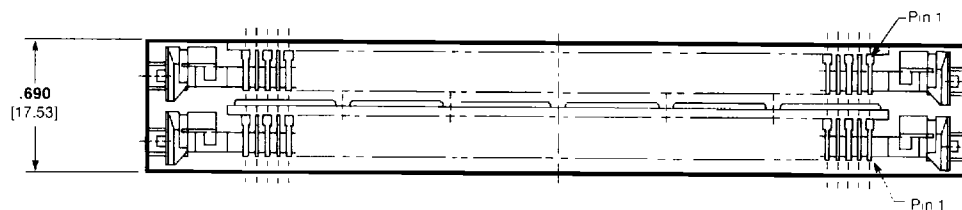
SIMM Sockets — with Plastic Latches, .100 [2.54] CL (Continued)

Vertical Dual Row
(.100 x .400 [2.54 x 10.16]
Spacing)

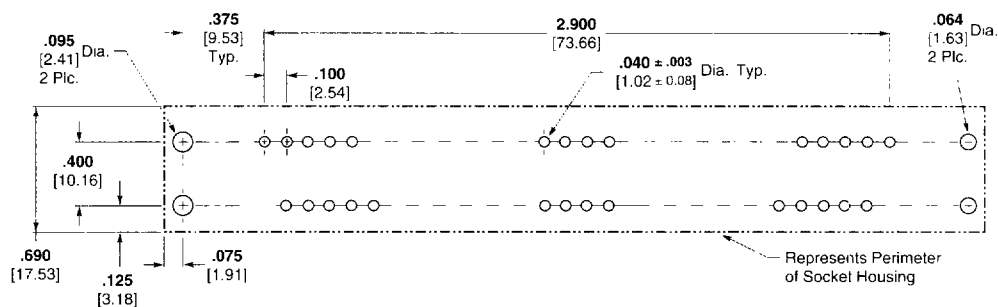
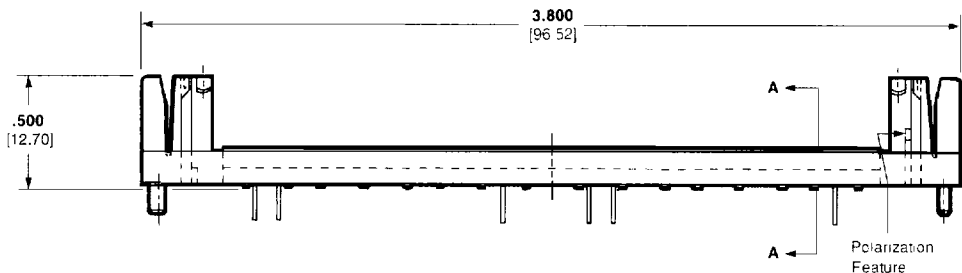
Material and Finish

Housing — Liquid Crystal Polymer (LCP) UL 94V-0

Contacts — Phosphor bronze with .000200 [0.00508] min. thick tin-lead over .000050 [0.00127] min. thick nickel on contact area and .000150 [0.0038] min. thick tin-lead on solder tails, all over .000050 [0.00127] min. thick nickel



Section A-A



Recommended PC Board Hole Pattern

No. of Pos.	Tin Plate
30	821830-2

Notes:

- See page 30 for module layout.
- Other sizes can be made available. Contact AMP Incorporated.

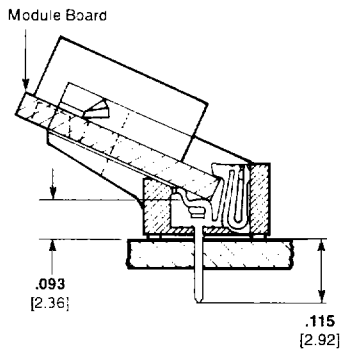
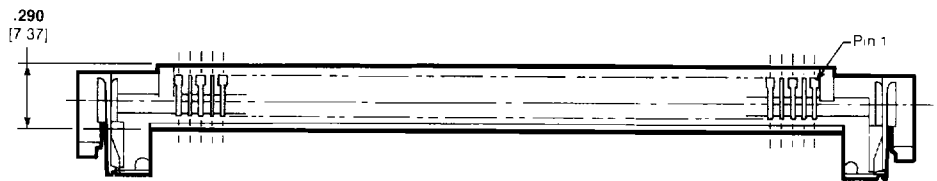
SIMM Sockets — with Plastic Latches, .100 [2.54] CL (Continued)

Low Profile (25°) Single Row

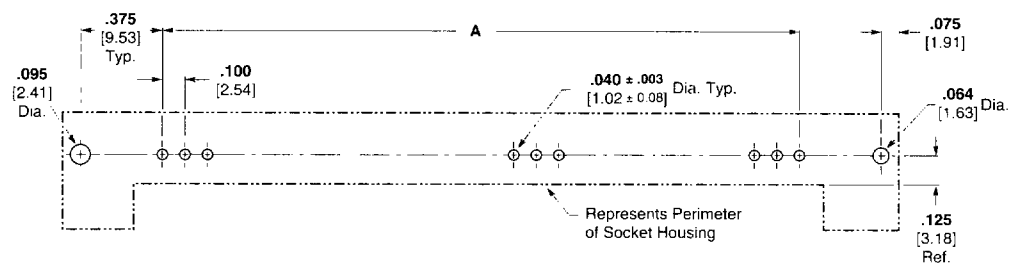
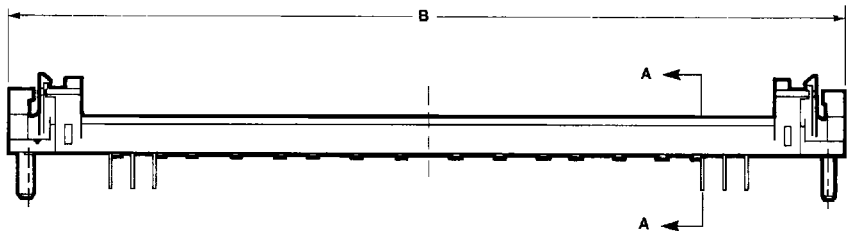
Material and Finish

Housing — Liquid Crystal Polymer (LCP) UL 94V-0

Contacts — Phosphor bronze with .000200 [0.00508] min. thick tin-lead over .000050 [0.00127] min. thick nickel or .000030 [0.00076] min. thick gold on contact area and .000150 [0.0038] min. thick tin-lead on solder tails, all over .000050 [0.00127] min. thick nickel



Section A-A



Recommended PC Board Hole Pattern

No. of Pos.	Dimensions		Tin Plate	Gold Plate
	A	B		
30	2.900 73.66	3.800 96.52	821876-2	821877-2
40	3.900 99.06	4.800 121.92	821876-4	—

Notes: 1. See page 30 for module layout.
2. Other sizes can be made available. Contact AMP Incorporated.

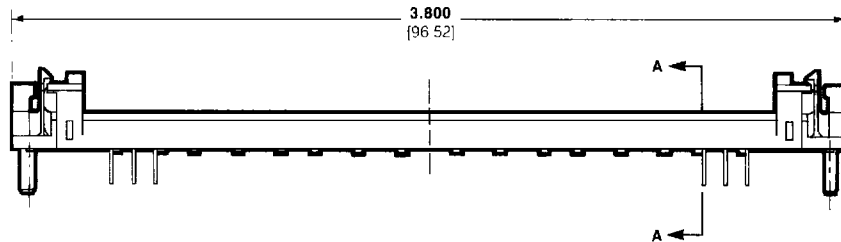
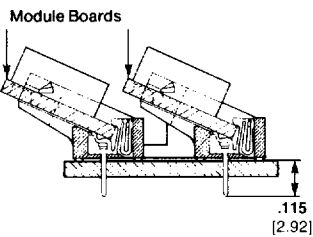
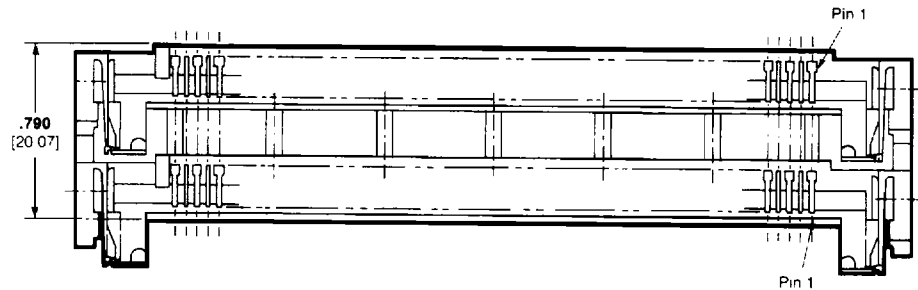
SIMM Sockets — with Plastic Latches, .100 [2.54] CL (Continued)

Low Profile Dual Row

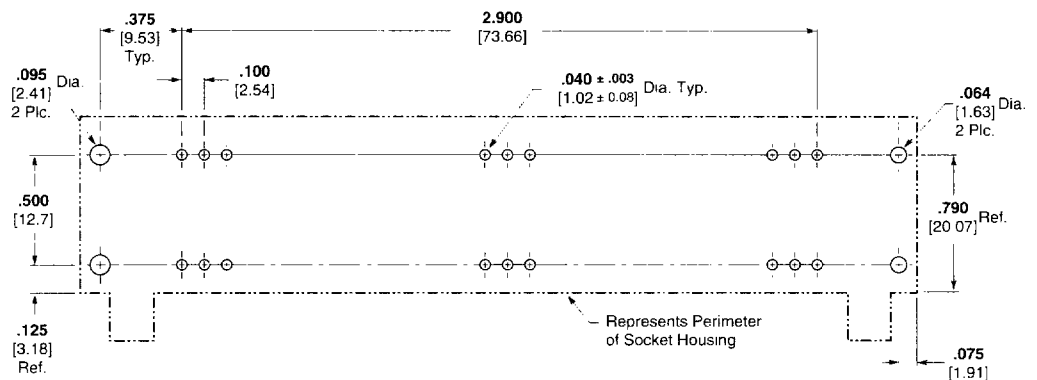
Material and Finish

Housing — Liquid Crystal Polymer (LCP) UL 94V-0

Contacts — Phosphor bronze with .000200 [0.00508] min. thick tin-lead over .000050 [0.00127] min. thick nickel or .000030 [0.00076] min. thick gold on contact area and .000150 [0.0038] min. thick tin-lead on solder tails, all over .000050 [0.00127] min. thick nickel



Section A-A



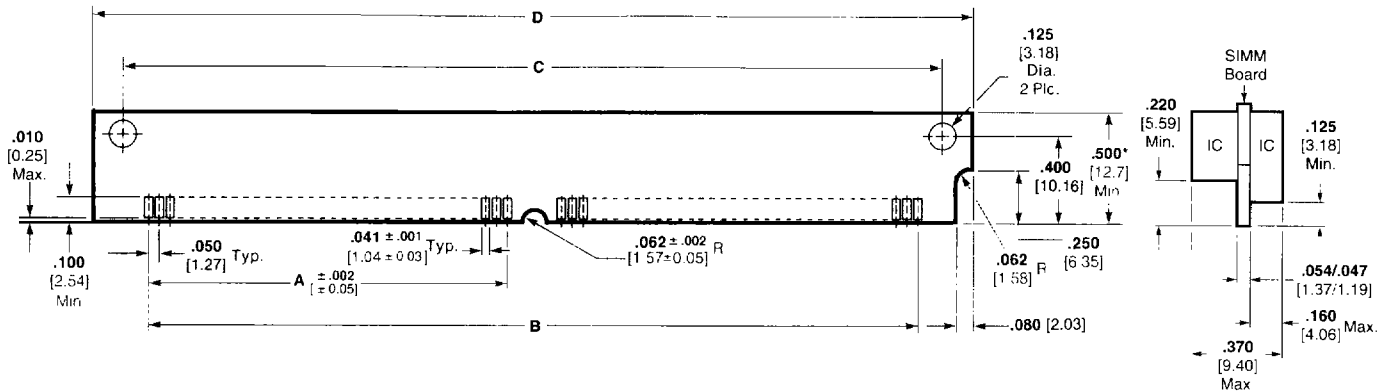
Recommended PC Board Hole Pattern

No. of Pos.	Tin Plate	Gold Plate
30	821832-2	821850-2

Notes: 1. See page 30 for module layout.
2. Other sizes can be made available. Contact AMP Incorporated.

SIMM Sockets — (MICRO-EDGE) Recommended Module Layouts

.050 [1.27] Centerline Module

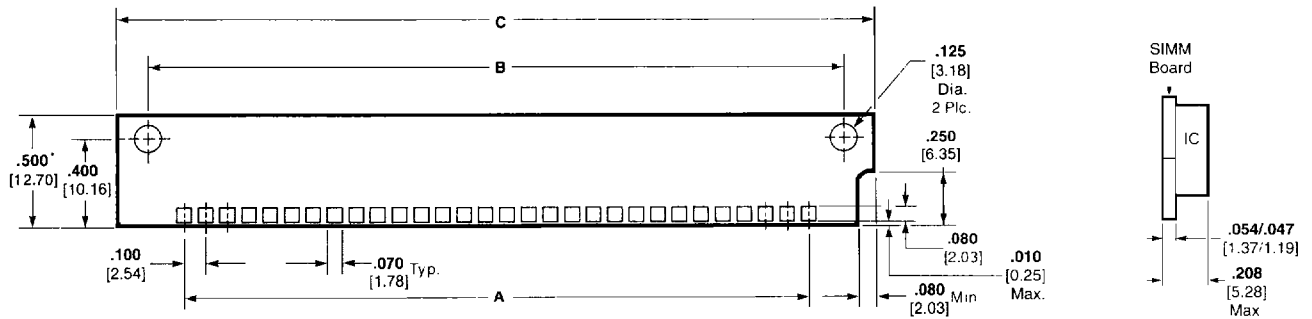


No. of Pos.	Dimensions			
	A	B	C	D
64	1.550 39.37	3.350 85.09	3.584 91.03	3.850 97.79
68	1.650 41.91	3.550 90.17	3.784 96.11	4.050 102.87
72	1.750 44.45	3.750 95.25	3.984 101.19	4.250 107.95
80	1.950 49.53	4.150 105.41	4.384 111.35	4.650 118.11

Notes: 1. .100 x .041 [2.54 x 1.04] pad area to be free via holes.
2. Tabs to be electronically connected on both sides of card.

* Heights in excess of 1.000 [25.4], consult AMP Incorporated.

.100 [2.54] Centerline Module



No. of Pos.	Dimensions		
	A	B	C
22	2.100 53.34	2.434 61.82	2.700 68.58
30	2.900 73.66	3.234 82.14	3.500 88.90
35	3.400 86.36	3.734 94.84	4.000 101.60
40	3.900 99.06	4.234 107.54	4.500 114.30
42	4.100 104.14	4.434 112.62	4.700 119.38

Notes: 1. .100 x .0421 [2.54 x 1.04] pad area to be free via holes.
2. Tabs to be electronically connected on both sides of card.

* Heights in excess of 1.00 [25.4], consult AMP Incorporated.